



Material Content Data Sheet



Sales Product Name		TLF50281EL		Issued		28. August 2013		
MA#		MA001048696						
Package		PG-SSOP-14-3		Weight*		83.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.105	3.72	3.72	37154	37154
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		412	
	non noble metal	iron	7439-89-6	0.689	0.82		8246	
wire	non noble metal	copper	7440-50-8	27.978	33.48	34.35	334809	343570
	noble metal	gold	7440-57-5	0.213	0.25	0.25	2544	2544
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1155
encapsulation	plastics	epoxy resin	-	4.440	5.31		53131	
	inorganic material	silicondioxide	60676-86-0	43.722	52.32	57.75	523223	577509
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11681	11681
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9186	9186
glue	plastics	epoxy resin	-	0.383	0.46		4589	
	noble metal	silver	7440-22-4	1.150	1.38	1.84	13767	18356
*deviation	< 10%					Sum in total:	100,00	1000000

Important Remarks:

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